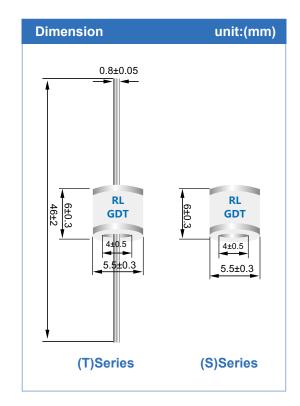


Gas Discharge Tube

2R075~2R600(S,T)A/B-5 Series

GDTs (Gas Discharge Tubes) are placed in front of, and in parallel with, sensitive telecom equipment such as power lines, communication lines, signal lines and data transmission lines to help protect them from damage caused by transient surge voltages that may result from lightning strikes and equipment switching operations. These devices do not influence the signal in normal operation. However, in the event of an overvoltage surge, such as a lightning strike, the GDT switches to a low impedance state and diverts the energy away from the sensitive equipment.

GDTs offer a high level of surge protection, a broad voltage range, low capacitance, and many form factors including new surface mount devices, which makes them suitable for applications such as MDF (Main Distribution Frame) modules, high data-rate telecom applications (e.g. ADSL, VDSL), and surge protection on power lines. Their low capacitance also results in less signal distortion. When used in a coordinated circuit protection solution with PTC devices, TSS thyristor surge protection devices, and MOV (Metal Oxide Varistor) devices, they can help equipment manufacturers meet



Features

- RoHS compliant and Lead-free
- GHz working frequency
- · Excellent stability on multiple pulse duty cycle
- Excellent response to fast rising transients.
- Ultra Low Insertion Loss
- 5KA/10KA surge capability tested with 8/20µS pulse as defined by IEC 6100-4-5
- Ultra small devices offered in a variety of mounting lead forms
- Non-Radioactive
- Low capacitance (<1.5pF)
- Voltage Ranges 75V to 600V
- UL recognized
- Conforms to ITU-T K12,IEC6100-4-5

Applications

- Communication equipment
- CATV equipment
- Test equipment
- Data lines
- Power supplies
- Telecom SLIC protection

- · Broadband equipment
- ADSL equipment including ADSL2+
- XDSL equipment
- Satellite and CATV equipment
- · General telecom equipment

Electriacl Characteristics								
Type Number	DC Spark-over voltage	Maximum Impulse spark-over voltage	Impuise life	Minimum Insulation resistance		Maximum Capacitance	Maximum surge Discharge Current	AC Dischare Curiren
	100v/s	1kv/us	10/1000us,100A	Test Voltage		1MHz	8/20us,10times	50Hz 1ses
	V	V	Times	DC(V)	GΩ	pF	KA	А
2R075(T,S)A-5	75±20%	800		DC 2 >1G				
2R090(T,S)A-5	90±20%	700		DC 50V >1GΩ		1pF	5КА	5A
2R150(T,S)A-5	150±20%	700						
2R230(T,S)A-5	230±20%	700		DC 100V >1GΩ				
2R300(T,S)A-5	300±20%	900						
2R350(T,S)A-5	350±20%	900						
2R400(T,S)A-5	400±20%	900						
2R420(T,S)A-5	420±20%	1000		DC 250V >1GΩ				
2R470(T,S)A-5	470±20%	1200						
2R600(T,S)A-5	600±20%	1500	300 times					
2R075(T,S)B-5	75±20%	600	300 times	DC 25V >1GΩ			10KA	10A
2R090(T,S)B-5	90±20%	700		DC 50V >1GΩ				
2R150(T,S)B-5	150±20%	700						
2R230(T,S)B-5	230±20%	800		DC 100V >1GΩ				
2R300(T,S)B-5	300±20%	800						
2R350(T,S)B-5	350±20%	1000						
2R400(T,S)B-5	400±20%	1100						
2R420(T,S)B-5	420±20%	1100		DC 250V >1GΩ				
2R470(T,S)B-5	470±20%	1200						
2R600(T,S)B-5	600±20%	1500						

Notes:

1.Insulation resistance measure at:

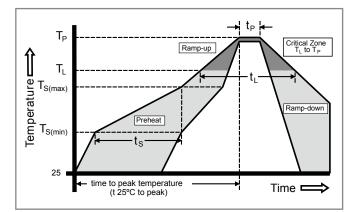
BC 50V for the 2R075,2R090,anB 2R150

BC 100V for other.

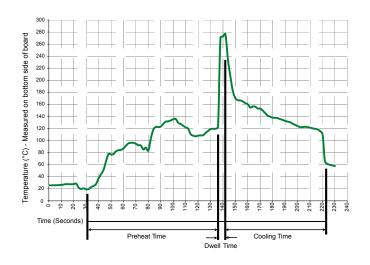
2. Terms in accorBance with ITU-T K.12 anB GA/T 9043-1005 3. At Belivery AQL 0.65 level 2 BIN ISO 2559

Soldering Parameters - Reflow Soldering (Surface Mount Devices)

Reflow Cor	ndition	Pb – Free assembly		
Pre Heat	-Temperature Min (T s(min))	150°C		
	-Temperature Max (T s(max))	200°C		
	-Time (Min to Max) (t _s)	60 – 180 secs		
Average ra (T _L) to peal	mp up rate (Liquidus Temp k	3°C/second max		
T _{S(max)} to T	- Ramp-up Rate	5°C/second max		
Reflow	-Temperature (T L) (Liquidus)	217°C		
	-Temperature (t L)	60 – 150 seconds		
Peak Temp	erature (T _P)	260 ^{+0/-5} °C		
Time withir Temperatu	n 5°C of actual peak re (t $_{\rm p})$	10 – 30 seconds		
Ramp-dow	n Rate	6°C/second max		
Time 25°C	to peak Temperature (T $_{\rm P}$)	8 minutes Max.		
Do not exc	eed	260°C		



Soldering Parameters - Wave Soldering (Thru-Hole Devices)



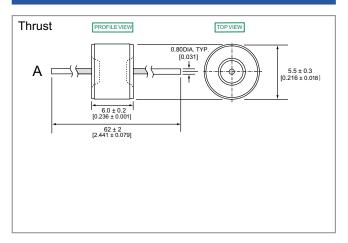
Soldering Parameters - Hand Soldering

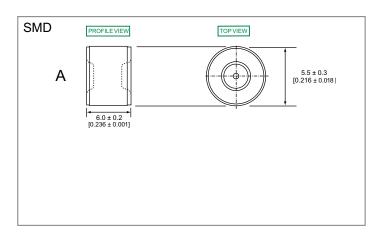
Solder Iron Temperature: 350° C +/- 5°C Heating Time: 5 seconds max.

Recommended Process Parameters:

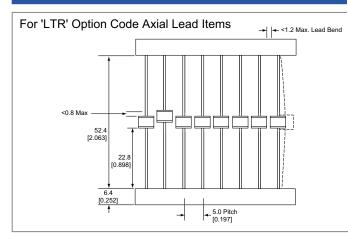
Wave Parameter	Lead-Free Recommendation			
Preheat: (Depends on Flux Activation Temperature)	(Typical Industry Recommendation)			
Temperature Minimum:	100° C			
Temperature Maximum:	150° C			
Preheat Time:	60-180 seconds			
Solder Pot Temperature:	280° C Maximum			
Solder Dwell Time:	2-5 seconds			

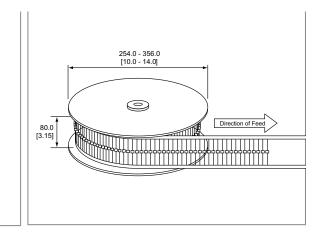
Device Dimensions



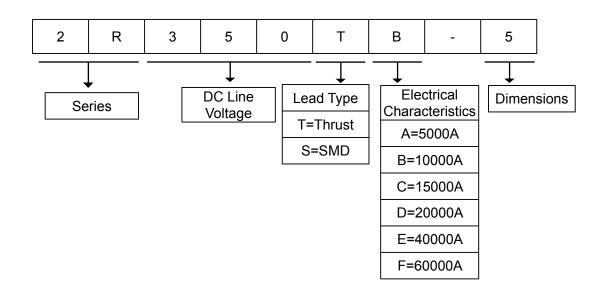


Packaging Dimensions





Part Number Code



RUILONG.YUAN CO.,LTD Tel: +86- 0755-82908296 Fax: +86- 0755-82908002 Email: jack@ruilon.com Website: http://www.ruilon.com

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